Chip Design Marketing and Lead Generation Programs Connect You with Real Buyers in the Advanced IC Design Market

Informing Chip and SoC design decision makers with unparalleled technology and business insights

Chip Design’s in-depth magazine, convenient email newsletters and content-rich websites are seen by more than 120,000 engineering and management professionals in 101 countries each month. These influential professionals rely on Chip Design for SoC design, EDA, ASICs, IP, FPGAs, RF, and Low Power design articles and product information.

Chip Design ensures our content and your message reach buyers worldwide in the formats they prefer, including:

- **www.ChipDesignMag.com**: Purchase influencers research suppliers and products online using the Chip Design portal’s informative articles, video library, news, research, white papers, and featured solutions guide.

- **Premium Content Channel**: System Design Engineering. Our editors create valuable content featuring our sponsors and their technology and deliver it to their target audience.

- **Magazine**: Our qualified audience of buyers is the largest and most diverse served by any Chip Design-focused magazine. They rely on our leading-edge and strategic articles and commentary to help make EDA; ASICs, FPGAs and PLD Design; IP and test development tools and equipment technology decisions.

- **Email Newsletters**: Design engineers and engineering managers working on advanced SoC designs stay informed by reading Chip Designer and IP Designer & Integrator for important industry news, product information, research, videos and more.

- **Events**: Semiconductor design and manufacturing industry leaders gather each year at The Confab to connect, collaborate and create the future. Executives and Engineers involved in the Multicore and IoT industries gather each year at the Multicore DevCon and Internet of Things Developers Conference.

**Audience Demographics**

System architect, design and test engineers and engineering managers working on advanced SoC designs—Chip Design readers—account for a third of all design engineers. These key enablers influence the purchase of nearly 80% of the total EDA market—or about $4 billion.

**Circulation by Job Responsibility**

<table>
<thead>
<tr>
<th>Engineering</th>
<th>Engineering Management</th>
<th>Executive &amp; other Management</th>
<th>Other (R&amp;D etc.)</th>
</tr>
</thead>
<tbody>
<tr>
<td>53.4%</td>
<td>27.9%</td>
<td>13.3%</td>
<td>5.4%</td>
</tr>
</tbody>
</table>

**Circulation breakdown by Purchasing Responsibility**

<table>
<thead>
<tr>
<th>Specify/Authorize/Influence the purchase of</th>
<th>Specify/Authorize/Influence the purchase of</th>
</tr>
</thead>
<tbody>
<tr>
<td>ASICs, FPGAs and PLDs</td>
<td>Standard ICs Services</td>
</tr>
<tr>
<td>94.8%</td>
<td>52.9%</td>
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</table>

<table>
<thead>
<tr>
<th>Specify/Authorize/Influence the purchase of</th>
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</thead>
<tbody>
<tr>
<td>Test Equipment/Development Tools</td>
</tr>
<tr>
<td>70.1%</td>
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</table>

<table>
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<tr>
<th>Specify/Authorize/Influence the purchase of</th>
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<tbody>
<tr>
<td>Intellectual Property</td>
</tr>
<tr>
<td>57.2%</td>
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</table>

<table>
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<tr>
<th>Specify/Authorize/Influence the purchase of</th>
</tr>
</thead>
<tbody>
<tr>
<td>Other (R&amp;D etc.)</td>
</tr>
<tr>
<td>5.4%</td>
</tr>
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</table>

**Top 30 Subscribing Companies**

<table>
<thead>
<tr>
<th>Altera</th>
<th>AMD</th>
<th>Analog Devices</th>
<th>Atmel</th>
<th>Broadcom</th>
<th>Cypress Semiconductor</th>
<th>Cisco</th>
<th>Freescale</th>
<th>Fujitsu</th>
<th>GLOBALFOUNDRIES</th>
</tr>
</thead>
<tbody>
<tr>
<td>IBM</td>
<td>IDT</td>
<td>Infineon</td>
<td>Intel</td>
<td>Hewlett-Packard</td>
<td>LSI</td>
<td>Marvell</td>
<td>Maxim Integrated</td>
<td>NVIDIA</td>
<td>NXP Semiconductors</td>
</tr>
<tr>
<td>ON Semiconductor</td>
<td>Oracle</td>
<td>PMC-Sierra</td>
<td>Qualcomm</td>
<td>Rohm Semiconductor</td>
<td>Samsung Electronics</td>
<td>ST Microelectronics</td>
<td>Texas Instruments</td>
<td>VIA Technologies</td>
<td>Xilinx</td>
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<tr>
<td>57.2%</td>
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</tbody>
</table>

<table>
<thead>
<tr>
<th>Specify/Authorize or authorize the purchasing at companies with revenues of over $500 million.</th>
</tr>
</thead>
<tbody>
<tr>
<td>35.6%</td>
</tr>
</tbody>
</table>
Chip Design Magazine & Engineers’ Guides focused on specific markets (FPGA’s; RF and Microwave; Sensors & MEMs)

- Chip Design Magazine - 40,000 qualified subscribers
- Engineers’ Guide to FPGA & PLD - 35,000 qualified subscribers
- Engineers’ Guide to Sensors & MEMs - 40,000 qualified subscribers
- RF & Microwave Systems - 32,500 qualified subscribers

Bonus Distribution: DAC, DesignCon, ARM TechCon, DATE, DevCon, Semicon West, Embedded World, IoT DevCon, Embedded Systems Conference

Email Newsletters: Reach targeted audiences with Chip Design Email Newsletters

Chip Design e-Newsletter (Bi-monthly): 45,000 Subscribers
IP Designer – Integrator e-Newsletter (Monthly): 33,000 Subscribers
RF & Microwave Systems e-newsletter (Quarterly): 30,000 Subscribers
FPGA & CPLD Quarterly Update e-newsletter: 36,000 Subscribers

Platinum Sponsor - Exclusive
468x80 banner at top center position and first text ad - $2,000/issue

Gold Sponsor - Exclusive
Skyscraper top right banner position and second text ad - $1,500/issue

Silver Sponsor - Exclusive
Second/third from top 125 x 125 banner position and third/fourth text ad - $1,000/issue

Magazine Net Rate
Two-page Spread $3,950
Full Page $2,500
Half Page $1,750
Back Cover $4,000
Inside Back Cover $3,500
Inside Front Cover Spread $3,750
Page 1 $3,500

Product Showcase Rates
Full Page Product Showcase $1,250
(Additional products 50% off)
1/2 page Product Showcase Net Rate: $950
(Additional products 35% off)

Dedicated Email Blasts
- Featured in six issues of Chip Designer e-Newsletter & Monthly White Paper Resource Newsletter distributed to over 50,000 subscribers.
- Dedicated Email Blasts
- Generate powerful leads with Chip Design Dedicated Email Blasts
- $295 cpm
- 15,000 minimum list size

Marketing & Lead Generation Programs Connect with Targets

Online, Lead Generation, Dedicated Email Blasts & Product Marketing

Online Presence:
- www.chipdesignmag.com
- www.eecatalog.com/fpga
- www.chipdesignmag.com/rfmw

“Spotlight On” Position (limited to 2 companies)
High impact and above the fold
Price - $4,000 per month

Banners
- Leaderboard (728x90) - $100 cpm
- Large Rectangle (336x280) - $100 cpm
- Half Page (300x600) - $100 cpm
- Welcome Page (800x600) - $450 cpm
- Exclusive “Push Down” Banner - High Impact banner expands to a maximum of 970 x 418 and then retracts to 970 x 90

Video Showcase Program:
- $1,000; $2,500 for editorial interview
- Video Showcase Program:
  • Exclusive “Push Down” Banner - High Impact
  • Welcome Page (800x600) - $450 cpm
  • Leaderboard (728x90) - $100 cpm
- Banners
  - Price - $4,000 per month
  - High impact and above the fold (limited to 2 companies)

“Spotlight On” Position
Create valuable content featuring your company and technology and deliver it to your target audience through the entire Chip Design Network

To learn more how you company can sponsor the Chip Design Premium Content Channel, Contact Gabe Moretti at gmoretti@extensionmedia.com

DVCon/DATE & DAC Special Offers

Magazine Incentives
Advertisers in the DVCon/Date and DAC show issues receive:
- Resource Guide Product Showcase FREE in the Summer/Fall issue

Video Showcase Program
- Promote a new product or announcement on camera at DAC
- Your video will be recorded at the event then posted on the Chip Design website and promoted in eight issues of Chip Designer to more than 40,000 SoC Designer decision makers
- PLUS, you receive a copy of the video to post on your site or YouTube and use for other marketing efforts
- Net rate $1,750; $2,500 for editorial interview

Product Showcase Newsletter - 35,000 Subscribers
Get exposure for your products, drive traffic to your booth and reach those unable to attend the show with a listing in the Product Showcase e-Newsletter.

- Product Listing: $750
- Leaderboard - $1,500 net
- Skyscraper on right rail - $1,500 net
- Silver (125x125) - $750 net (limited availability)

DAC E-Daily - 35,000 Subscribers
Leverage Chip Design’s DAC coverage by positioning your advertising in our special e-Show Daily e-Newsletter and on ChipDesignMag.com distributed daily during DAC (June 8-10). The daily newsletter goes out to over 35,000 subscribers.

- Platinum $2,500
- Gold $2,000
- Silver #1 $1,000
- Silver #2 $1,000
- Silver #3 $1,000

Market Surveys | Lead Generation
Each quarter in 2016, Chip Design will conduct a Market Intelligence Survey of its readership. Data collected includes industry trends, buying preferences, key factors influencing purchasing and evaluation decisions and much more including contact data on all respondents. Custom surveys also available upon request

2016 Market Intelligence/Lead Generation Topics
IP Integration — February
RF/Microwave — April
EDA Tech & Tools — June
Verification — September
EDA Tech & Tools — November/December

Sponsorship net rate: $3,950 (sponsor may add up to 3 proprietary questions at an additional fee of $2,500 per program)

Sign-up for all 4 surveys for $12,500

Chip Design Premium Content Channel
Create valuable content featuring your company and technology and deliver it to your target audience through the entire Chip Design Network
May 25-26, 2016 | Hyatt Regency | Santa Clara

- The Biggest and most important IoT conference of the year dedicated to IoT technology in Semiconductor Design & Embedded Systems
- 1,300 Pre-qualified attendees in 2015

### Contact Us

**EDITORIAL**

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### 2016 Editorial Calendar

<table>
<thead>
<tr>
<th>Magazine</th>
<th>Focus Reports</th>
<th>Market Research</th>
<th>E-Newsletters</th>
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</table>
| **WINTER/SPRING ISSUE** | Ad Close: Jan 14  
Material: Jan 16  
Semiconductor HW-SW CoDesign Processors Low Power IP Modeling | DesignCon (Santa Clara, CA)  
Embedded World (Nuremberg, Germany)  
DV Con 2016 (San Jose, CA)  
DATE (Dresden, Germany)  
IP Integration EDA Tech & Tools | Jan. 14, 28  
Feb. 10, 24  
Mar. 16, 30  
Apr. 13, 27  
May 10, 25  
Jan. 21  
Feb. 17  
Mar. 23  
Apr. 20  
May 18  
Feb. 11  
Jan. 14  
Feb. 4 |
| **RF AND MICROWAVE SYSTEM** | Ad Close: April 6  
Material: April 10  
Wearable Electronics and RF/Microwave for IoT RF/Microwave IP Telecommunications RFID Packaging Considerations Testing Beyond 40 GHz | IMS 2016 DAC (San Francisco) Mobile World Congress 2017  
RF/Microwave Chip Design/Test | Special Issue  
Sponsored by IMS 2016 |
| **SUMMER/FALL ISSUE** | Ad Close: May 14  
Material: May 16  
Designing Sub-10nm ICs Design Troubleshooting Analysis and Debugging Tools Design Automation for the IoT Chip-Package-Board Co-Design Power, Performance, Area (PPA) Optimization Understanding Giga-Scale Challenges | DRC (San Francisco, CA)  
Semicon West (San Francisco, CA)  
Digital Only  
Annual Resource Guide  
Verification EDA Tech & Tools Webcast Chip Design for the Internet of Things | June 15, 29  
July 13, 27  
Aug. 17, 31  
Sept. 14, 28  
Oct. 12, 26  
Nov. 10  
June 22  
July 21  
Aug. 18  
Sept. 22  
Oct. 20  
Nov. 17  
Aug. 18  
July 14  
Aug. 4  
Nov. 10  
Oct. 13  
Aug. 3  |
| **WINTER/SPRING ISSUE** | Ad Close: Dec 5  
Material: Dec 10  
Design for Automotive System Level Design Power Management Virtual Prototyping IP Selection, Reuse How to Design for 3D Integration | DesignCon 2017 (Santa Clara, CA) Embedded World DVCOn DATE | Nov. 30  
Dec. 7, 14  
Dec. 15  
Feb. 3, 2016 |

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**Face to Face Opportunities**

Co-located with Internet of Things Developers Conference  
The Multicore DevCon brings together engineers and executives to participate in a forum dedicated to multicore technology and learn about products and tools from a practical perspective.